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NAN YA PLASTICS CORPORATION
ELECTRONIC MATERIALS DIVISION.
COPPER CLAD LAMINATE DEPARTMENT

NO. 201. TUNG HWA N. ROAD,
TAIPEI, TAIWAN.

Glass cloth base epoxy resin
flame retardant copper clad laminate

NP-140TL

■ FEATURES

- Multi-functional epoxy renders the material outstanding heat resistance, better dimensional stability, and through-hole reliability that benefit the performance of high layer count multilayer boards.
- HTE copper foil applied to prevent corner cracking.
- High luminance of epoxy contrast with copper for laser type A.O.I.
- UV solder mask may be applied simultaneously in order to increase yields.
- IPC-4101B specification is applicable.

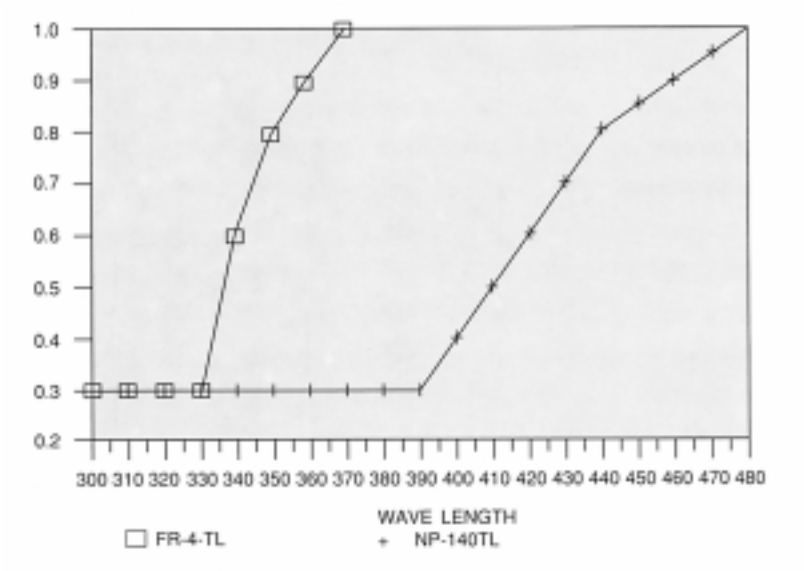
■ PERFORMANCE LIST

Characteristics	Unit	Conditioning	Typical Values	SPEC	Test Method
Volume resistivity	MΩ-cm	C-96/35/90	5.0 x10^9	10^6 ↑	2.5.17
Surface resistivity	MΩ	C-96/35/90	5.0 x10^7	10^4 ↑	2.5.17
Permittivity 1 MHZ	-	C-24/23/50	4.2-4.4	5.4 ↓	2.5.5.9
Permittivity 1 GHZ	-	C-24/23/50	3.8-4.0	-	2.5.5.9
Loss Tangent 1 MHZ	-	C-24/23/50	0.015-0.020	0.035 ↓	2.5.5.9
Loss Tangent 1 GHZ	-	C-24/23/50	0.012-0.014	-	2.5.5.9
Arc resistance	SEC	D-48/50+D-0.5/23	120 ↑	60 ↑	2.5.1
Dielectric breakdown	KV	D-48/50	60 ↑	40 ↑	2.5.6
Moisture absorption	%	D-24/23	0.20-0.30	0.35 ↓	2.6.2.1
Flammability	-	C-48/23/50	94V0	94V0	UL94
Peel strength 1 oz	lb/in	288°Cx10" solder floating	10-14	6 ↑	2.4.8
Thermal stress	SEC	288°C solder dipping	90 ↑	10 ↑	2.4.13.1
Glass transition temp	°C	DSC	140 ± 5	N/A	2.4.25
Dimensional stability X-Y axis	%	E 4/105	0.01-0.03	0.05 ↓	2.4.39
Coefficient of thermal expansion Z-axis before Tg Z-axis after Tg	ppm/°C ppm/°C	TMA TMA	50-70 250-350	N/A	2.4.24

Data shown are nominal values for reference only.

NOTE:
The average value in the table refers to samples of .020" 1/1.
Test method per IPC-TM-650

■ UV TRANSMISSION CURVE OF 0.2mm CCL



■ PRODUCT SIZE & THICKNESS

THICKNESS INCH(mm)	COPPER CLADDING OZ (μm)	SIZE INCH	SIZE mm	THICKNESS TOLERANCE
0.004 (0.1)	0.5 (17)	48.8 x 36.6	1240 x 0930	
to	1.0 (35)	48.8 x 40.5	1240 x 1030	CLASS C/M
0.047 (1.2)	2.0 (70)	48.8 x 42.5	1240 x 1080	

■ Keeping the core and prepreg in the same grain direction is crucial to ensure the flatness of multilayer boards.

Grain direction is shown on the Certificate of Conformance

■ CERTIFICATION UL

・UL File No. : E98983

■ CONSTRUCTION:

THICKNESS mm	THICKNESS mil	CONSTRUCTION	
0.08	3	2112	1 ply
0.10	4	1080	2 plies
0.11	4	2116	1 ply
0.13	5	1080	2 plies
0.13sp	5	2116	1 ply
0.15	6	1506	1 ply
0.16	6	2112	2 plies
0.21	8	7628	1 ply
0.26	10	2116	2 plies
0.30	12	2116	3 plies
0.30sp	12	1506	2 plies
0.35	14	7628	2 plies
0.38	15	7628	2 plies

THICKNESS mm	THICKNESS mil	CONSTRUCTION	
0.45	18	7628 x 2 + 1080 x 1	
0.46	18	7667	2 plies
0.50	20	7628	3 plies
0.53	21	7628	3 plies
0.60	24	7628	3 plies
0.77	31	7628	4 plies
0.8	32	7628	4 plies
0.9	36	7628	5 plies
1.0	39	7628	5 plies
1.1	43	7628	6 plies
1.2	47	7628	6 plies

*1.2,1.1,1.0,0.9,0.77 mm, THICKNESS INCLUDES CLADDING. ALL OTHERS EXCLUDE CLADDING.